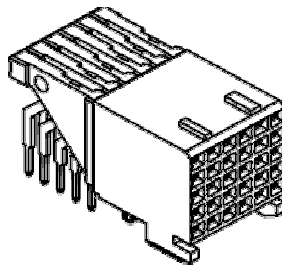
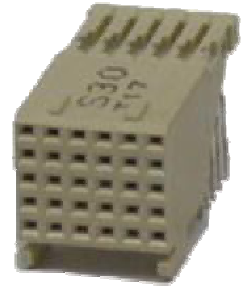


PerMet 2.0 5x6 Signal PIH

According to IEC 61076-4-104



- Designed according to the standard IEC 61076-4-104 in such a way that machine assembly and Reflow soldering is possible
- High contact density with 2 mm grid spacing
- 12 mm connector module
- Termination method: paste in hole

PRODUCT DATA

Electric data

Current rating	1 A max / contact
Test voltage	1000 V AC (rms)
Insulation resistance	5 Gohm (min)
Temperature range	-55... +125 °C

Materials

Housing material	Thermoplastic resin, glass-fibre filled, UL 94 V-0
Contact material	Copper alloy
Contact plating	Gold over nickel or.. Gold flash over nickel palladium over nickel
Terminal plating	Tin over nickel

Physical data

Mating force	0.45 N max / contact
Withdrawal Force	0.15 N min / contact

PCB data

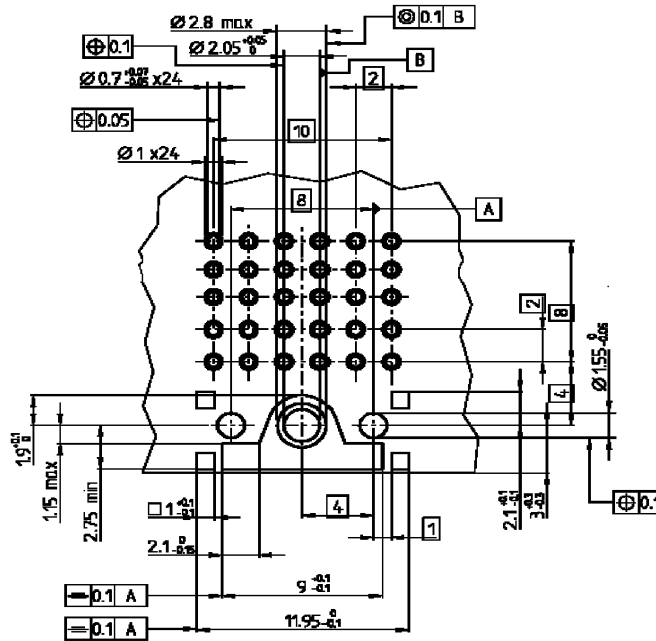
Recommended PCB hole platings	0.7 ^{+0.07} / _{-0.05} mm
PCB Thickness	Cu 25-50 µm, Sn or SnPb < 10 µm
	1.6 – 2.4 mm

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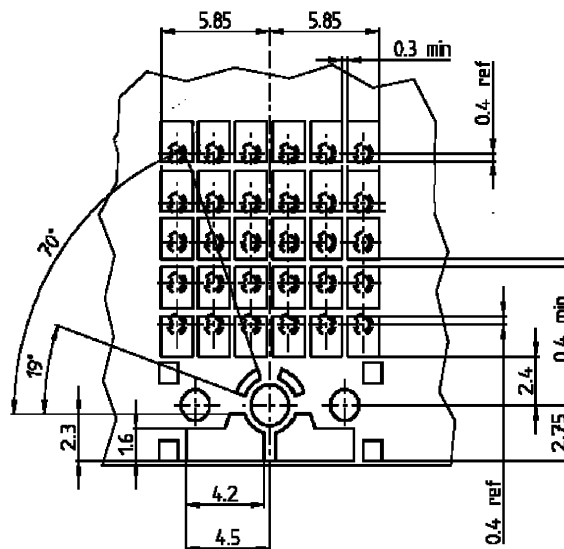


PerMet 2.0 5x6 Signal PIH

Recommended PCB layout



Recommended stencil layout



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